

Press Release

Innovation is in our DNA – Viscom at productronica 2019

Hannover, 9 October 2019 – As a technology leader for optical and X-ray inspection systems for electronics manufacturing, Viscom will be presenting several new developments in Munich from November 12-15 at productronica 2019, the world's leading trade show in this sector. The focus is on smart-factory solutions that minimize cycle time, increase process efficiency and prevent defects, thus ensuring greater safety and reliability in SMT production. This requires innovations such as AI-assisted verification, ultra-fast inspection speeds and seamless, high-precision defect inspection of sophisticated assemblies. In addition, trends such as e-mobility, new energy technologies, LEDs and high-performance electronics require new inspection solutions, for example the innovative inline X-ray inspection system with integrated workpiece carrier handling developed by Viscom.

In the area of X-ray technology we have now expanded our wide range of offline and inline X-ray systems to include a further innovation: developed specifically for the most sophisticated high-performance electronics and components for e-mobility and renewable energy, our new **X8068 SL** inline system carries out fully automated inspections of large and solid inspection objects. The inline X-ray system is equipped with an impressive integrated transport system with workpiece carriers and inspects the connection of semiconductors and other quality-relevant areas such as surface solder joints with a perfect combination of speed and precision. Viscom offers a customer-specific adaptation of the system to facilitate seamless integration in the production line – a sound investment for the future.

Viscom has already showcased a new milestone in fast, high-precision inline X-ray inspection with our **X7056-II** system, which has won multiple

international awards for its innovative machine design. Offering the fastest complete AXI inspection and the outstanding advantages of combined 3D AOI and 3D AXI inspection in a single system, this X-ray solution is establishing itself as the new standard – both as a combined system and as a X-ray only machine – in state-of-the-art SMT lines around the globe. The X7056-II ensures accurate inspection of hidden solder joints and components in high-volume production. The 3D reconstruction of the X7056-II is based on planar computer tomography, which makes invisible defects clearly visible in sharp slice images. At productronica you can experience the system firsthand at Viscom's trade show stand under the intuitive vVision operating interface, which guarantees ultra-fast generation and optimization of inspection plans.

Viscom's many years of development expertise in the area of 3D AOI have now led to a very special innovation: the new **S3016 ultra, a bottom-side system that guarantees** outstanding, high-throughput, **3D inspection from below** of THT solder joints and pressfit connections **for the first time**.

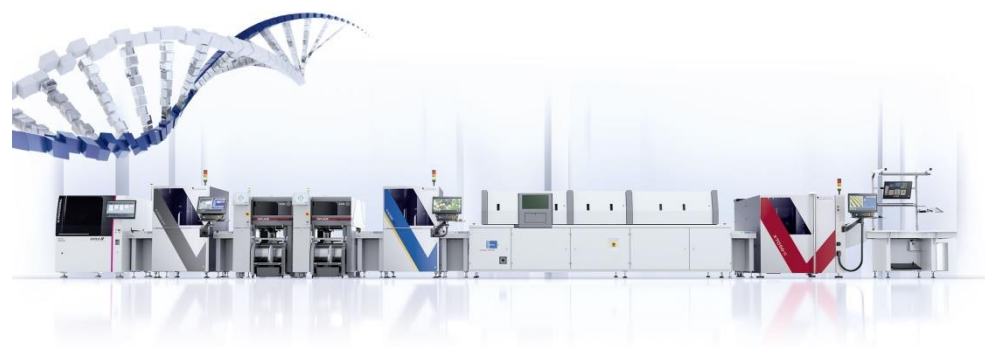
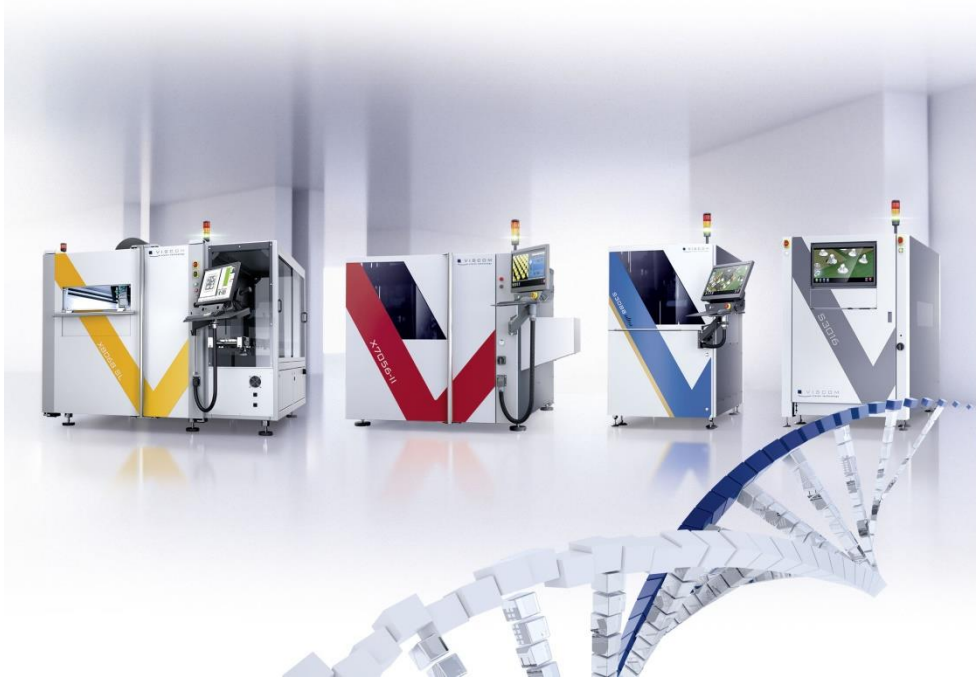
Moreover, Viscom is now offering a unique range of sensor technology for the new **S3088 DT** system, which is designed for maximum efficiency dual-lane operation in series production. The system configuration is extremely flexible to facilitate a wide range of fully automatic inspections, including 3D AOI, 3D SPI, CCI and UFI. This in turn ensures optimal inspection quality and maximum throughput in placement, solder joint, solder paste, conformal coating and underfill inspection.

Visitors to productronica will not want to miss the **3D AOI Arena** in hall A2, where numerous manufacturers are presenting their 3D AOI systems for comparison. You can see the premium **S3088 ultra gold** from Viscom in action and how it delivers the most reliable 3D AOI inspection results with optimal, nearly shadow-free image quality and realistic 360° views.

To meet the most demanding **smart factory** requirements, Viscom offers open interfaces and in-house software solutions to integrate the advanced inspection systems perfectly in Industry 4.0 process lines. Particularly with regard to smart maintenance and traceability, Viscom offers intelligent concepts that prevent defects right from the start, significantly increase production efficiency and elevate inspection system performance to the highest level. For optimized and absolutely reliable verification, we are also presenting a trailblazing software concept utilizing artificial intelligence.

Viscom will be exhibiting its innovative and comprehensive range of 3D SPI, 3D AOI, 3D AXI, MXI, CCI and Bond inspection solutions in **Hall A2, Stand number 177.**

Images



About Viscom

Viscom AG develops, manufactures, and sells high-quality inspection systems. Our range encompasses the full spectrum of optical and X-ray inspection systems. Viscom is one of the world's leading providers of assembly inspection systems for the electronics manufacturing industry. Systems from Viscom can be networked and customized to meet specific customer needs. Our headquarters and production site are located in Hannover, Germany. Viscom has a wide international network of subsidiaries, applications centers, service centers and representatives. Founded in 1984, Viscom has been listed on the Frankfurt Stock Exchange (ISIN: DE0007846867) since 2006. For further information, visit www.viscom.com.